



(0.80 mm) .0315"

HSEC8-DV SERIES

# VERTICAL EDGE RATE® CARD SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com/HSEC8-DV](http://www.samtec.com/HSEC8-DV)

### Insulator Material:

Black Liquid Crystal Polymer

### Contact:

BeCu

### Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

### Current Rating:

2.8 A per pin  
(2 adjacent pins powered)

### Operating Temp:

-55 °C to +125 °C

### RoHS Compliant:

Yes

### Card Mates:

(1.60 mm) .062" card,  
(2.36 mm) .093" card,  
HSC8

### Cable Mates:

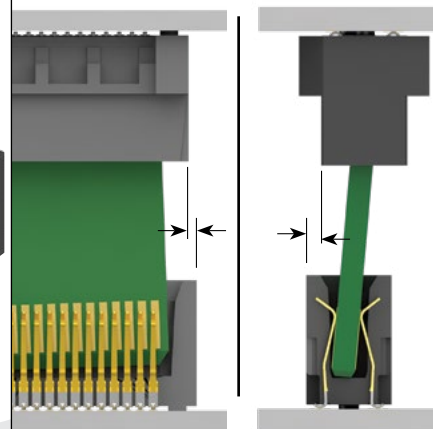
ECDP



Mates with (1.60 mm) .062"  
or (2.36 mm) .093" cards



## MISALIGNMENT MITIGATION



Custom designs compensate for misalignment.

## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (10-60)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## HIGH-SPEED CHANNEL PERFORMANCE

### HSEC8-DV

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

28  
Gbps

HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

09, 10, 13, 20,  
25, 30, 37, 40, 49,  
50, 60, 70, 80, 100  
(13, 25, 49 only available  
with -L or -L2 option;  
09 only available with -L2 option;  
37 only available with -L option)

-01  
= (1.60 mm) .062"  
thick card

-03  
= (2.36 mm) .093"  
thick card

-L  
= 10 μ" (0.25 μm)  
Gold on contact,  
Matte Tin on tail

-S  
= 30 μ" (0.76 μm)  
Gold on contact,  
Matte Tin on tail

-K  
= (7.01 mm) .276" DIA Polyimide Film  
Pick & Place Pad; with -01 card,  
= (6.25 mm) .246" DIA Polyimide Film  
Pick & Place Pad; with -03 card

-BL  
= Board Locks -01 card only  
(Weld tab standard)

-L  
= Latching Option; -01 card only  
(13, 25, 37, 49 only)  
(Weld tab standard)

-L2  
= ECDP Latching; -01 card only  
(09, 13, 25, 49 only)  
(For use with ECDP)  
(Weld tab standard)

-WT  
= Weld tab

-TR  
= Tape & Reel  
(09 - 70 only)

-FR  
= Full Reel Tape & Reel Packaging  
(Must order max. quantities per reel.  
Contact Samtec for parts per reel)  
(09 - 70 only)

| CABLE   | CONNECTOR    |
|---------|--------------|
| ECDP-04 | HSEC8-109-L2 |
| ECDP-08 | HSEC8-113-L2 |
| ECDP-16 | HSEC8-125-L2 |
| ECDP-32 | HSEC8-149-L2 |

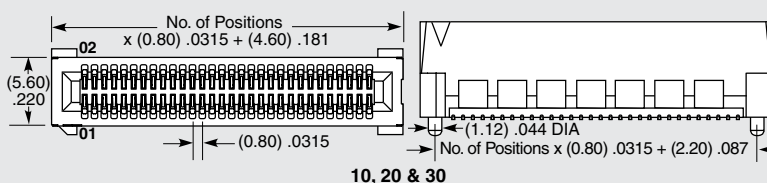
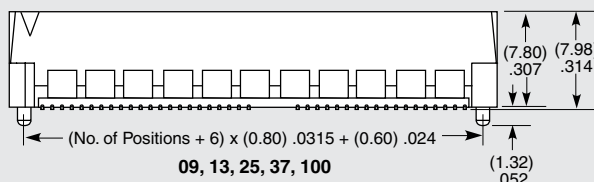
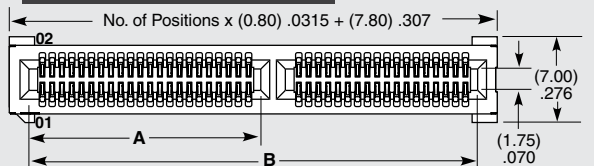
| POSITIONS PER ROW | A             | B             |
|-------------------|---------------|---------------|
| 09†               | (4.50) .177   | (11.80) .465  |
| 13†               | (6.10) .240   | (15.00) .591  |
| 25†               | (6.10) .240   | (24.60) .969  |
| 37†               | (18.10) .713  | (34.20) 1.346 |
| 40                | (18.90) .744  | (36.60) 1.441 |
| 49†               | (22.90) .902  | (43.80) 1.724 |
| 50                | (22.90) .902  | (44.60) 1.756 |
| 60                | (26.90) 1.059 | (52.60) 2.071 |
| 70†               | (26.90) 1.059 | (60.60) 2.386 |
| 80†               | (26.90) 1.059 | (68.60) 2.701 |
| 100†              | (26.90) 1.059 | (84.60) 3.331 |

Positions where no dimensions are given do not have keying feature.  
\* Mates with ECDP Series.  
† Available with -01 Card Only.

### Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.  
Components must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.